

# $Surface\ Mount-600V-800V\ >\ BTA16-600SW3G,\ BTA16-800SW3G,$

## **Maximum Ratings** $(T_J = 25^{\circ}C \text{ unless otherwise noted})$

**Thyristors** 

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1) (Gate Open, Sine Wave 50 to 60 Hz, $T_J$ = -40° to 125°C) BTA16-600SW3G BTA16-800SW3G	V <sub>drm</sub> , V <sub>rrm</sub>	600 800	V
On-State RMS Current (Full Cycle Sine Wave, 60 Hz, $T_{\rm C}$ = 25°C	I <sub>T (RMS)</sub>	16	А
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, T <sub>C</sub> = 25°C)	I <sub>TSM</sub>	170	А
Circuit Fusing Consideration (t = 8.3 ms)	l²t	120	A²sec
Non-Repetitive Surge Peak Off-State Voltage ( $T_J = 25$ °C, $t = 8.3$ ms)	$V_{DSM}/V_{RSM}$	V <sub>DSM</sub> /V <sub>RSM</sub> +100	V
Peak Gate Current (T <sub>J</sub> = 110°C, t ≤20 μs)	I <sub>GM</sub>	4.0	А
Peak Gate Power (Pulse Width≤ 20 μs, T <sub>C</sub> = 80°C)	P <sub>GM</sub>	20	W
Average Gate Power ( $T_J = 125$ °C)	P <sub>G(AV)</sub>	1.0	W
Operating Junction Temperature Range	Т	-40 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +125	°C
RMS Isolation Voltage (t = 300 ms, R.H. $\leq$ 30%, $T_A$ = 25°C)	V <sub>iso</sub>	2500	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### **Thermal Characteristics**

Rating		Symbol	Value	Unit
Thermal Resistance,	Junction-to-Case (AC) Junction-to-Ambient	R <sub>sJC</sub>	2.13 60	°C/W
Maximum Lead Temperature for Sold 10 seconds	ering Purposes, 1/8" from case for	$T_{L}$	260	°C

<sup>1.</sup>  $V_{DRM}$  and  $V_{RRM}$  for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.



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## **Electrical Characteristics** • **OFF** (T<sub>1</sub> = 25°C unless otherwise noted; Electricals apply in both directions)

**Thyristors** 

Characteristic		Symbol	Min	Тур	Max	Unit
Peak Repetitive Blocking Current	$T_{_{\rm J}} = 25^{\circ}\text{C}$	I <sub>DRM</sub> ,	-	-	0.005	
$(V_D = V_{DRM} = V_{RRM}, Gate Open)$	$T_J = 110^{\circ}C$	IRRM	-	-	2.0	mA

## **Electrical Characteristics** - **ON** $(T_J = 25^{\circ}\text{C unless otherwise noted; Electricals apply in both directions)$

Characteristic		Symbol	Min	Тур	Max	Unit
Forward On-State Voltage (Note 2) ( $I_{TM} = \pm 22.5 \text{ A Peak}$ )		V <sub>TM</sub>	_	_	1.55	V
Gate Trigger Current (Continuous dc) ( $V_D = 12 \text{ V}, R_L = 30 \Omega$ )	MT2(+), G(+)		2.0	-	10	
	MT2(+), G(-)	l <sub>GT</sub>	2.0	-	10	mA
	MT2(-), G(-)		2.0	_	10	
Holding Current $(V_D = 12 \text{ V, Gate Open, Initiating Current} = \pm 500 \text{ mA})$		I <sub>H</sub>	_	_	20	mA
	MT2(+), G(+)		_	_	25	
Latching Current ( $V_D = 12 \text{ V}, I_G = 12 \text{ mA}$ )	MT2(+), G(-)	I <sub>L</sub>	-	-	30	mA
	MT2(-), G(-)		-	_	25	
	MT2(+), G(+)		0.5	-	1.3	
Gate Trigger Voltage ( $V_D = 12 \text{ V}, R_L = 30 \Omega$ )	MT2(+), G(-)	V <sub>GT</sub>	0.5	_	1.3	V
	MT2(-), G(-)		0.5	-	1.3	
	MT2(+), G(+)		0.2	-	-	
Gate Non-Trigger Voltage (T <sub>J</sub> = 110°C)	MT2(+), G(-)	$V_{\rm GD}$	0.2	-	-	V
	MT2(-), G(-)		0.2	-	-	

<sup>2.</sup> Indicates Pulse Test: Pulse Width  $\leq$  2.0 ms, Duty Cycle  $\leq$  2%.



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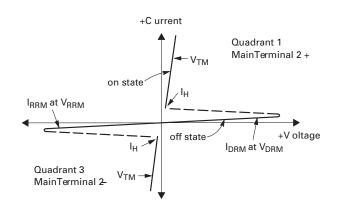
### **Dynamic Characteristics**

Characteristic		Min	Тур	Max	Unit
Rate of Change of Commutating Current, See Figure 10. (Gate Open, T <sub>J</sub> = 110°C, No Snubber)		2.0	_	_	A/ms
Critical Rate of Rise of On–State Current ( $T_J = 110$ °C, $f = 120$ Hz, $I_G = 20$ mA, $tr \le 100$ ns)	dl/dt	-	-	50	A/μs
Critical Rate of Rise of Off-State Voltage ( $V_D = 0.66 \times V_{DRM}$ , Exponential Waveform, Gate Open, $T_J = 110^{\circ}\text{C}$ )		250	_	_	V/µs

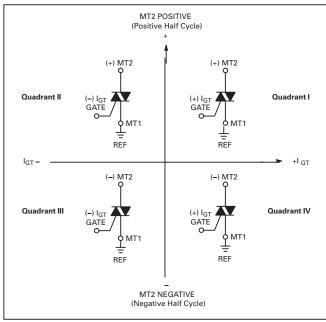
### **Voltage Current Characteristic of SCR**

Symbol	Parameter		
$V_{DRM}$	Peak Repetitive Forward Off State Voltage		
I <sub>DRM</sub>	Peak Forward Blocking Current		
V <sub>RRM</sub>	Peak Repetitive Reverse Off State Voltage		
I <sub>RRM</sub>	Peak Reverse Blocking Current		
V <sub>TM</sub>	Maximum On State Voltage		
I <sub>H</sub>	Holding Current		

**Thyristors** 



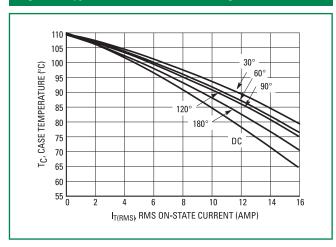
## **Quadrant Definitions for a Triac**



All polarities are referenced to MT1.
With in-phase signals (using standard AC lines) quadrants I and III are used.

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**Figure 1. Typical RMS Current Derating** 



**Thyristors** 

Figure 3. On-State Characteristics

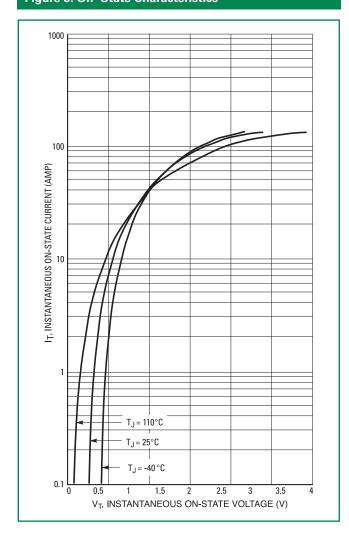
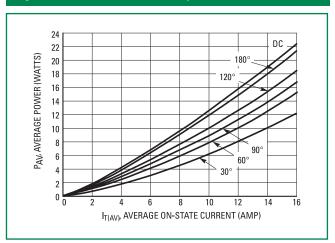


Figure 2. On-State Power Dissipation



**Figure 4. Thermal Response** 

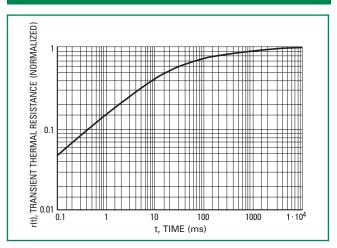


Figure 5. Hold Current Variation

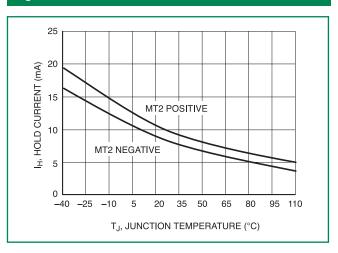
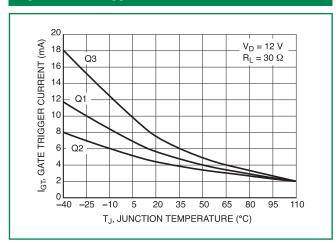
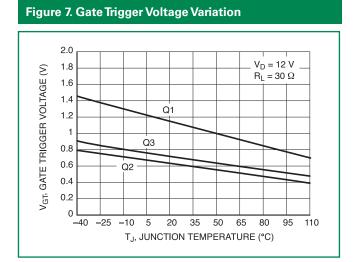




Figure 6. Gate Trigger Current Variation



**Thyristors** 



**Figure 8. Typical Latching Current Variation** 

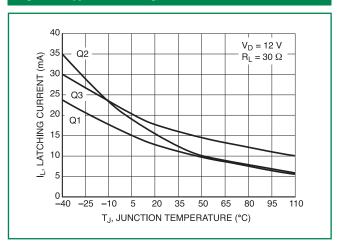
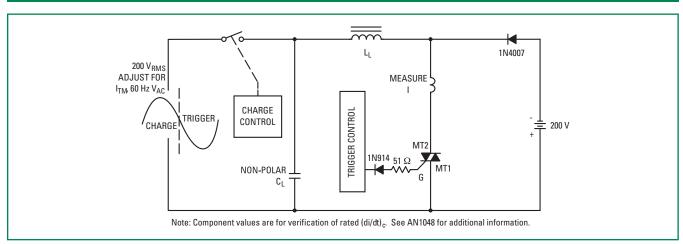


Figure 9. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Current (di/dt)

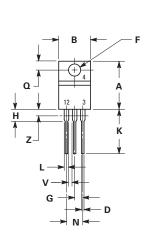


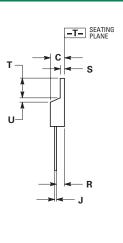
Note: Component values are for verification of rated (di/dt)c. See AN1048 for additional information



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#### **Dimensions**

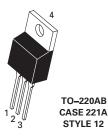


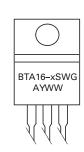


<u> </u>	Inches		Millim	neters	
Dim	Min	Max	Min	Max	
А	0.570	0.620	14.48	15.75	
В	0.380	0.405	9.66	10.28	
С	0.160	0.190	4.07	4.82	
D	0.025	0.035	0.64	0.88	
F	0.142	0.147	3.61	3.73	
G	0.095	0.105	2.42	2.66	
Н	0.110	0.155	2.80	3.93	
J	0.014	0.022	0.36	0.55	
K	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
N	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.39	
Т	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
V	0.045		1.15		
Z		0.080		2.04	

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

#### **Part Marking System**





x= 6 or 8

A= Assembly Location (Optional)\*

Y= Year WW = Work Week G= Pb-Free Package

\* The Assembly Location code (A) is optional. In cases where the Assembly Location is stamped on the package the assembly code may be blank.

Pin Assignment	
1	Main Terminal 1
2	Main Terminal 2
3	Gate
4	No Connection

#### **Ordering Information**

Device	Package	Shipping
BTA16-600SW3G	TO-220AB (Pb-Free)	50 Units / Rail
BTA16-800SW3G	TO-220AB (Pb-Free)	50 Units / Rail

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